

FORESEE ECC DDR4 UDIMM 2666 Datasheet

Version: 1.0





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Revision History

Revision No.	History	Draft Date	Remark
1.0 Release		Dec 2019	



1. Type

ECC DDR4 UDIMM 288PIN

2. Full conception

DDR4 SDRAM Unbuffered DIMM, It supports 1.2V low voltage mode. Design 288PIN golden finger interface protocols, and it supports two dual channel applications.

3. Design refer

JEDEC DDR4 R/C

4. Product Name

Workstation Memory

5. Capacity information

DDR4 32GB

6. Book Sheet

Туре	Capacity	Speed	HV P/N
ECC UDIMM	32 GB	2666	FD4AE2666CWGSM

7. Specification

Specification	JEDEC ECC DDR4 Reference	
Interface	DDR4 288PIN ECC UDIMM	
Capacity	32 GB	
Speed	2666Mbps	
CAS Latency	19	
Organization	2 Rank x8	
Voltage	1.2V	
Operating Temp.	0~85℃ (Surface)	
Storage Temp.	-40℃ ~ +85℃	
Form Factor	133.35 * 31.25 mm	
Application	Workstation (general reference)	



8. PCB Specifications

General

1. Board size: 133.35 * 31.25 mm ± 0.15 mm

2. Thickness: 1.2 ± 0.1 mm3. Pin count: 288 PIN

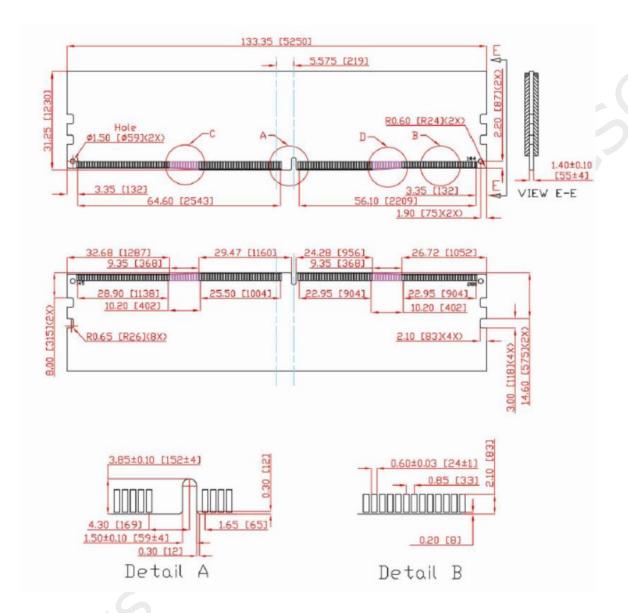
PCB Material

1. RoHS

2. Glass Epoxy FR4, .UL 94V-0



9. Module Dimensions



Units: millimeters